

DS-7402

(ANSI: FR-4) Halogen-Free

Features

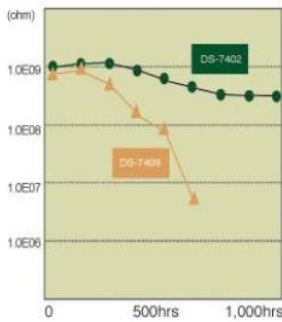
- Middle Tg (Tg 150°C)
- Halogen-free, antimony-free, and red phosphorus-free
- High decomposition temperature
- Low z-axis CTE
- Anti-CAF property

Applications

- Alternative for conventional lead-free FR-4
- Personal computer, Notebook computer
- Cellular phone, A/V Device, etc.

General Properties

● CAF Resistance Test Result

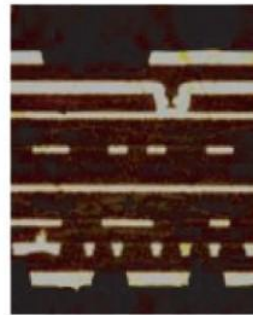


Test Coupon Construction



- Hole 0.3mm
- Pitch 0.7mm
- 85°C/85%RH/DC 50V

● Lead-free Soldering Test Result



- Test Condition
 - 8L PCB
 - THB (30°C, RH60%)
 - 168hr → Reflow 260°C
 - 3 cycles → TCT
 - 100 cycles
 - (-65°C ↔ 125°C)
- Test Result
 - No delamination
 - No crack

Property	Unit	Test Condition	Typical Value	Test Method
Tg	°C	DSC	150	IPC-TM-650.2.4.25c
		TMA	150	IPC-TM-650.2.4.24c
CTE Z-axis	ppm/°C	Ambient to Tg	45	IPC-TM-650.2.4.41
Z-axis Expansion	%	50°C to 260°C	3.0	IPC-TM-650.2.4.41
Decomposition Temperature (5% wt loss)	°C	TGA	370	IPC-TM-650.2.3.40
T-260	min	TMA	120	IPC-TM-650.2.4.24.1
T-288	min	TMA	> 60	IPC-TM-650.2.4.24.1
Dielectric Constant (Resin Content 50%)		C-24/23/50 (1GHz)	4.4	IPC-TM-650.2.5.5.9
Dissipation Factor (Resin Content 50%)		C-24/23/50 (1GHz)	0.014	IPC-TM-650.2.5.5.9
Peel Strength (Standard profile 1oz)	N/mm	Condition A	1.6	IPC-TM-650.2.4.8
Water Absorption	%	E-24/50+D-24/23	0.13	IPC-TM-650.2.6.2.1

* IPC-4101B/92

* Test specimen thickness: 1.0mm (7628x5)